

480-OUTPUT TFT-LCD SOURCE DRIVER (COMPATIBLE WITH 256-GRAY SCALES)

DESCRIPTION

The μ PD160088 is a source driver for TFT-LCDs capable of dealing with displays with 256-gray scales. Data input is based on digital input configured as 8 bits by 3 dots (1 pixel) with double clock edge, which can realize a full-color display of 16,700,000 colors by output of 256 values γ -corrected by an internal D/A converter and 9-by-2 external power modules. Because the output dynamic range is as large as $V_{SS2} + 0.1$ V to $V_{DD2} - 0.1$ V, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion, n-line inversion and column line inversion when mounted on a single side, this source driver is equipped with a built-in 8-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a clock frequency of 85 MHz when driving at 2.7 V, this driver is applicable to UXGA-standard (1600 x 1200), SXGA-standard (1280 x 1024) TFT-LCD panels.

FEATURES

- RSDS™ (Reduced Swing Differential Signaling) interface
- 480 Outputs
- Input of 8 bits (gradation data) by 3 dots with double clock edge
- Capable of outputting 256 values by means of 9-by-2 external power modules (18 units) and a D/A converter
- Logic power supply voltage (V_{DD1}): 2.7 to 3.6 V
- Driver power supply voltage (V_{DD2}): 10.5 to 13.5 V
- High-speed data transfer : $f_{CLK} = 85$ MHz MAX. (Internal data transfer speed when operating at $V_{DD1} = 2.7$ V)
- Output dynamic range : $V_{SS2} + 0.1$ V to $V_{DD2} - 0.1$ V
- Apply for dot-line inversion, n-line inversion and column line inversion
- Output voltage polarity inversion function (POL)
- Input data inversion function (INV)
- Controllable charge sharing function (MODE)

Remark RSDS™ is a trademark of National Semiconductor Corporation.

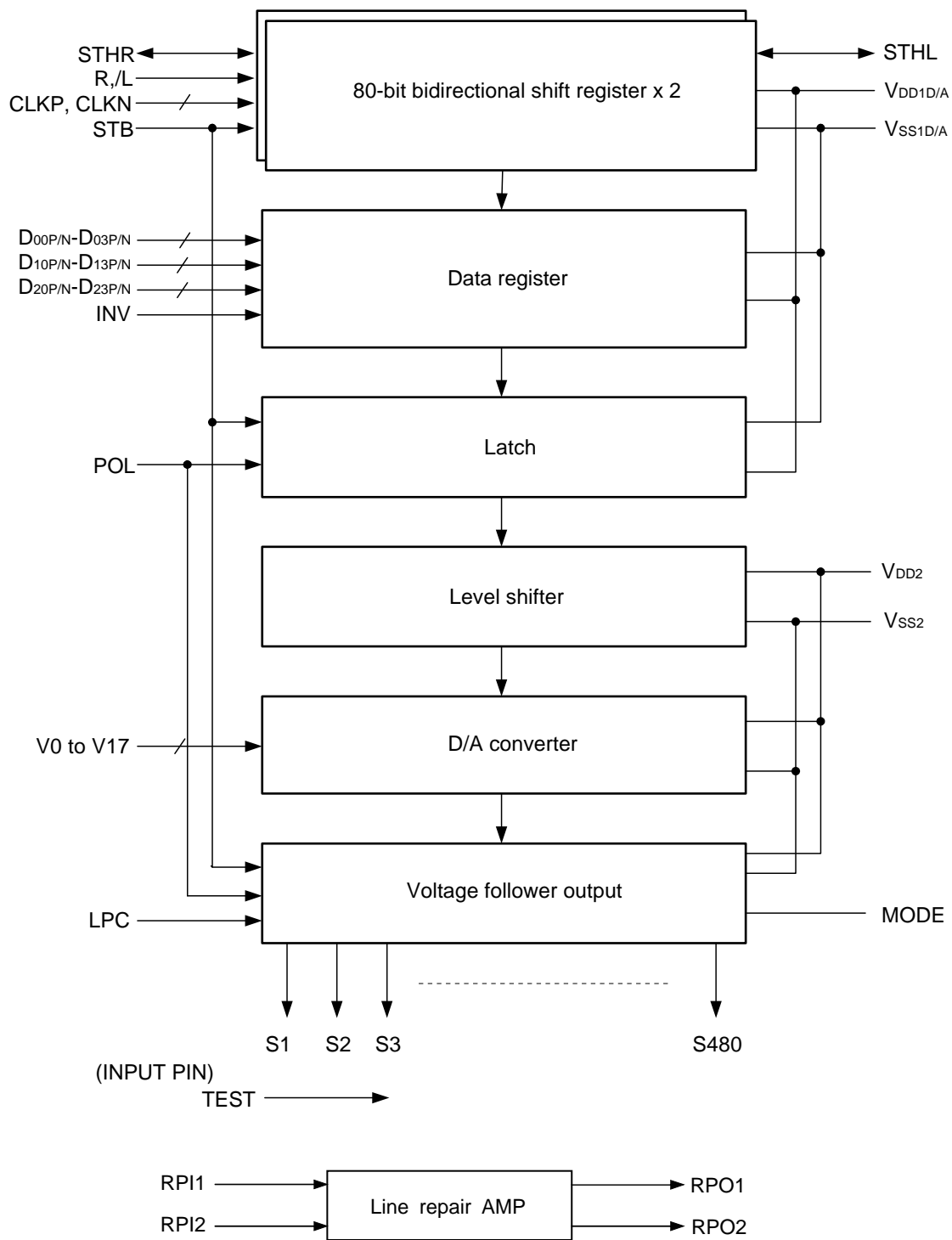
ORDERING INFORMATION

Part Number	Package
μ PD160088N-xxx	TCP (TAB package)
μ PD160088NL-xxx	COF (COF package)

Remark The TCP and COF's external shape is customized. To order the required shape, please contact one of our sales representatives.

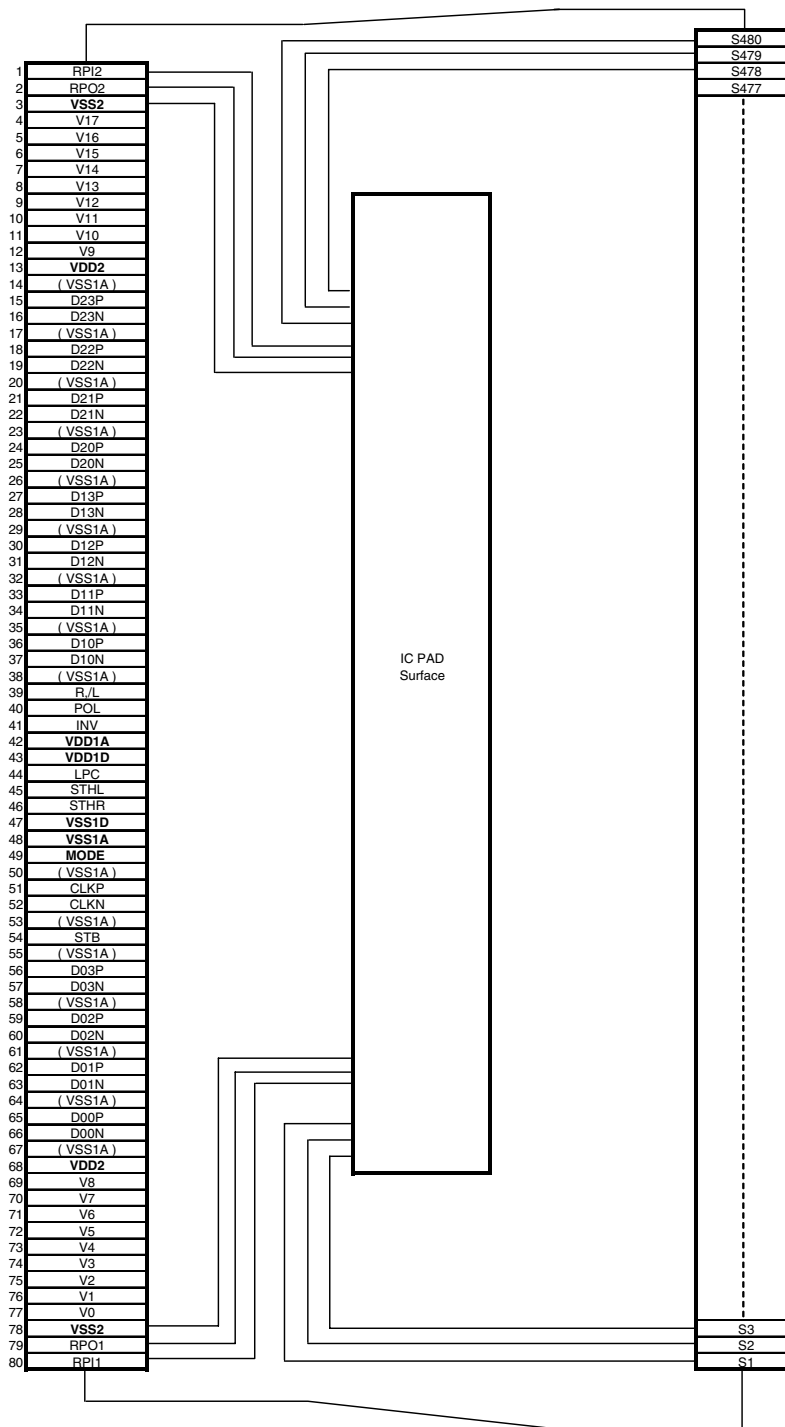
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Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.**

1. BLOCK DIAGRAM



Remark /xxx indicates active low signal.

2. PIN CONFIGURATION (μPD160088N-xxx: TCP, μPD160088NL-xxx: COF)



Remark This figure does not specify the TCP and COF package.

(VSS1A) is recommended to connect to analog GND on PCB for the return current of transmission line. And please don't use these pins for power supply terminal with dynamic current.

3. PIN FUNCTIONS

(1/2)

Pin Symbol	Pin Name	I/O	Description
S ₁ to S ₄₈₀	Driver	Output	The D/A converted 256-gray-scale analog voltage is output.
D _{00P} to D _{03P} , D _{00N} to D _{03N}	Display data (RSDS)	Input	The display data is input with a width of 12 bits by double edge, viz., the gray scale data (8 bits) by 3 dots (1 pixel).
D _{10P} to D _{13P} , D _{10N} to D _{13N}			
D _{20P} to D _{23P} , D _{20N} to D _{23N}			
R _{,L} (CMOS)	Shift direction control	Input	These refer to the start pulse input/output pins when driver ICs are connected in cascade. The shift directions of the shift registers are as follows. R _{,L} = H (V _{DD1} level): STHR input, S ₁ → S ₄₈₀ , STHL output R _{,L} = L (V _{SS1} level): STHL input, S ₄₈₀ → S ₁ , STHR output
STHR (CMOS)	Right shift start pulse	I/O	R _{,L} = H (V _{DD1} level): Becomes the start pulse input pin. R _{,L} = L (V _{SS1} level): Becomes the start pulse output pin.
STHL (CMOS)	Left shift start pulse	I/O	R _{,L} = H (V _{DD1} level): Becomes the start pulse output pin. R _{,L} = L (V _{SS1} level): Becomes the start pulse input pin.
CLKP, CLKN (RSDS)	Shift clock	Input	Refers to the shift register's shift clock input. The display data is incorporated into the data register at both of rising and falling edge. At the falling edge of the 160th clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver.
STB (CMOS)	Latch	Input	The contents of the data register are transferred to the latch circuit at the rising edge. And the output timing and charge sharing function are controlled by MODE. Please refer to 9. RELATIONSHIP BETWEEN MODE, STB, POL AND OUTPUTWAVEFORM for more detail. It is necessary to ensure input of one pulse per horizontal period.
POL (CMOS)	Polarity	Input	POL = H (V _{DD1} level): The S _{2n-1} output uses V ₀ -V ₈ as the reference supply. The S _{2n} output uses V ₉ -V ₁₇ as the reference supply. POL = L (V _{SS1} level): The S _{2n-1} output uses V ₉ -V ₁₇ as the reference supply. The S _{2n} output uses V ₀ -V ₈ as the reference supply. S _{2n-1} indicates the odd output and S _{2n} indicates the even output. Input of the POL signal is allowed the setup time (t _{POL-STB}) with respect to STB's rising edge.
INV (CMOS)	Data inversion	Input	Data inversion can invert when display data is loaded. INV = H (V _{DD1} level): Data inversion loads display data after inverting it. INV = L (V _{SS1} level): Data inversion does NOT INVERT input data. Please input DC signal. Refer to 6. DATA INVERSION .
LPC (CMOS)	Low Power Control	-	LPC = L or Open : Normal mode (default) LPC = H : Low power mode (30% lower than normal mode) This pin is pulled down to the V _{SS1D} inside the IC.
MODE (CMOS)	Charge Sharing Control	-	This pin control the Charge Sharing Function. MODE = H or Open : Disable MODE = L : Enable But Charge Sharing function works only when POL signal is changed from previous line. This pin is pulled up to V _{DD1D} inside the IC.
RPI1, RPI2	Line-repair AMP.	Input	The driver-ability of the line-repair amp is around twice of the normal analog output; S ₁ to S ₄₈₀ . And these outputs are changed at the rising edge of STB and don't have a Hi-Z period. RPI1 (RPI2) → impedance changed → RPO1 (RPO2)
RPO1, RPO2	Line-repair AMP.	Output	

Remark Hi-Z: High impedance

(2/2)

Pin Symbol	Pin Name	I/O	Description
TEST (CMOS)	Test	–	TEST = H or Open : Normal operation mode TEST = L : Test mode
V ₀ -V ₁₇	γ-corrected power supplies	–	Input the γ-corrected power supplies from outside by using operational amplifier. Make sure to maintain the following relationships. During the gray scale voltage output, be sure to keep the gray scale level power supply at a constant level. $V_{DD2} - 0.1 \text{ V} \geq V_0 > V_1 > V_2 > V_3 > V_4 > V_5 > V_6 > V_7 > V_8 \geq 0.5 V_{DD2}$ $0.5 V_{DD2} \geq V_9 > V_{10} > V_{11} > V_{12} > V_{13} > V_{14} > V_{15} > V_{16} > V_{17} \geq V_{SS2} + 0.1 \text{ V}$
V _{DD1D/A}	Logic power supply	–	2.7 to 3.6 V
V _{DD2}	Driver power supply	–	10.5 to 13.5 V
V _{SS1D/A}	Logic ground	–	Grounding
V _{SS2}	Driver ground	–	Grounding

- Cautions 1.** The power on sequence must be V_{DD1D/A}, logic input, and V_{DD2} and V₀-V₁₇ in that order. Reverse this sequence to shut down. (Simultaneous power application to V_{DD2} and V₀-V₁₇ is possible.)
- 2.** To stabilize the supply voltage, please be sure to insert a 0.1 μF bypass capacitor between V_{DD1D/A}-V_{SS1D/A} and V_{DD2}-V_{SS2}. Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about 0.01 μF is also advised between the γ-corrected power supply pins (V₀, V₁, V₂, .., V₁₇) and V_{SS2}.
 - 3.** Because of the large power consumption of this driver IC, it is necessary to pay attention to the driver IC's temperature for the Junction Temperature. So, it should be considered to use the suitable mechanical design for the heat spreading and use the LPC function and the output reset function for the power reduction. Especially, it is recommended to measure the temperature of the driver IC surface.

4. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

This product incorporates a 8-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode (common electrode) voltage. The D/A converter consists of ladder resistors and switches.

The ladder resistors (r_0 to r_{255}) are designed so that the ratio of LCD panel γ -compensated voltages to V_0' - V_{255}' and V_0'' - V_{255}'' is almost equivalent. For the 2 sets of 9 γ - compensated power supplies, V_0 - V_8 and V_9 - V_{17} , respectively, input gray scale voltages of the same polarity with respect to the common voltage.

Figure 4-1 shows the relationship between the driving voltages such as liquid-crystal driving voltages V_{DD2} and V_{SS2} , common electrode potential V_{COM} , and γ - corrected voltages V_0 - V_{17} and the input data. Be sure to maintain the voltage relationships of

$$V_{DD2} - 0.1 \text{ V} \geq V_0 > V_1 > V_2 > V_3 > V_4 > V_5 > V_6 > V_7 > V_8 \geq 0.5 V_{DD2}$$

$$0.5 V_{DD2} \geq V_9 > V_{10} > V_{11} > V_{12} > V_{13} > V_{14} > V_{15} > V_{16} > V_{17} \geq V_{SS2} + 0.1 \text{ V}$$

Figures 4-2 shows γ - corrected voltages and ladder resistors ratio and Figure 4-3 shows relationship between the input data and the output voltage.

Figure 4-1. Relationship between Input Data and γ - corrected Power Supply

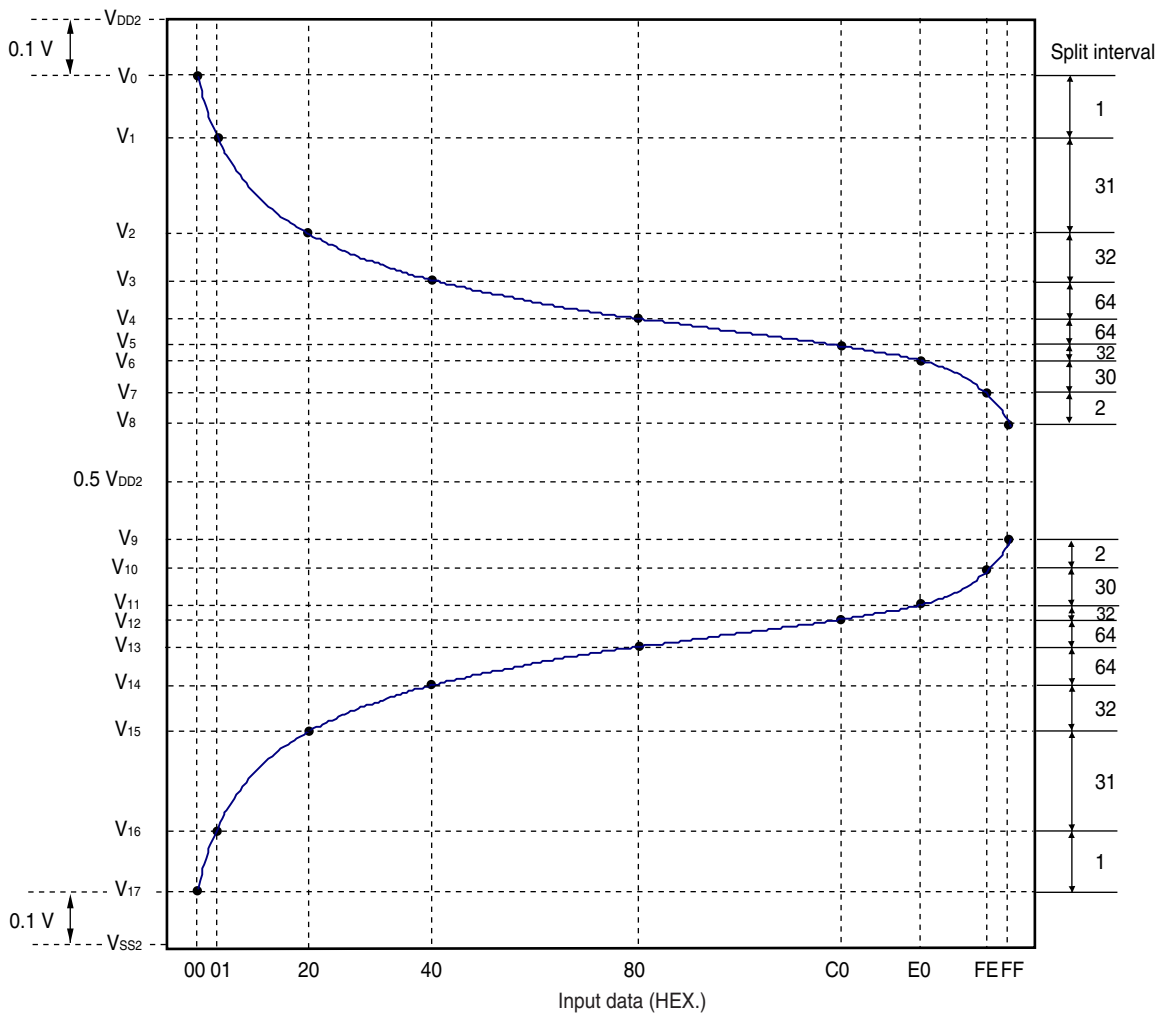
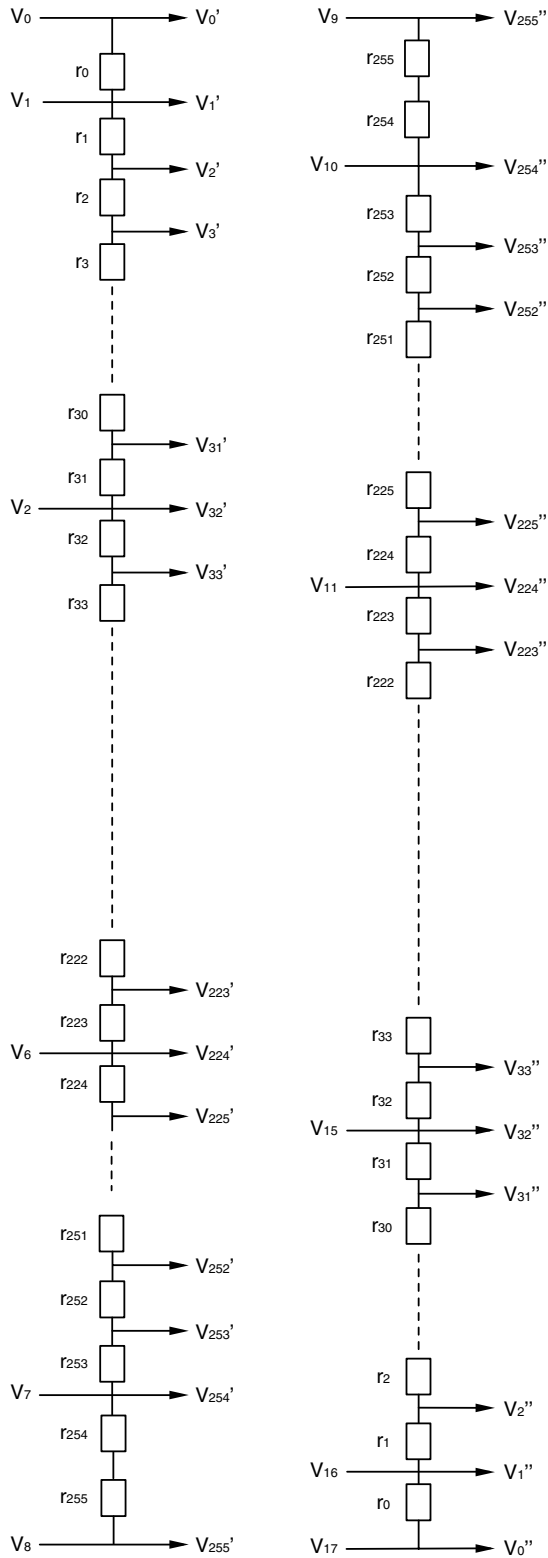


Figure 4-2. γ-corrected Voltages and Ladder Resistors Ratio



m	Ratio	Value	m	Ratio	Value	m	Ratio	Value	m	Ratio	Value
r0	31.50	630	r64	2.25	45	r128	1.00	20	r192	1.00	20
r1	27.50	550	r65	2.25	45	r129	1.00	20	r193	1.00	20
r2	24.00	480	r66	2.25	45	r130	1.00	20	r194	1.00	20
r3	21.50	430	r67	2.25	45	r131	1.00	20	r195	1.00	20
r4	19.00	380	r68	2.00	40	r132	1.00	20	r196	1.25	25
r5	17.50	350	r69	2.00	40	r133	1.00	20	r197	1.25	25
r6	16.50	330	r70	2.00	40	r134	1.00	20	r198	1.25	25
r7	15.00	300	r71	2.00	40	r135	1.00	20	r199	1.25	25
r8	14.00	280	r72	2.00	40	r136	1.00	20	r200	1.25	25
r9	13.00	260	r73	2.00	40	r137	1.00	20	r201	1.25	25
r10	12.00	240	r74	2.00	40	r138	1.00	20	r202	1.25	25
r11	11.00	220	r75	2.00	40	r139	1.00	20	r203	1.25	25
r12	10.00	200	r76	1.75	35	r140	1.00	20	r204	1.25	25
r13	9.50	190	r77	1.75	35	r141	1.00	20	r205	1.25	25
r14	9.50	190	r78	1.75	35	r142	1.00	20	r206	1.25	25
r15	9.00	180	r79	1.75	35	r143	1.00	20	r207	1.25	25
r16	8.50	170	r80	1.75	35	r144	1.00	20	r208	1.25	25
r17	8.00	160	r81	1.75	35	r145	1.00	20	r209	1.25	25
r18	7.50	150	r82	1.75	35	r146	1.00	20	r210	1.25	25
r19	7.50	150	r83	1.75	35	r147	1.00	20	r211	1.25	25
r20	7.00	140	r84	1.75	35	r148	1.00	20	r212	1.25	25
r21	6.50	130	r85	1.75	35	r149	1.00	20	r213	1.25	25
r22	6.50	130	r86	1.50	30	r150	1.00	20	r214	1.25	25
r23	6.00	120	r87	1.50	30	r151	1.00	20	r215	1.25	25
r24	6.00	120	r88	1.50	30	r152	1.00	20	r216	1.25	25
r25	5.50	110	r89	1.50	30	r153	1.00	20	r217	1.25	25
r26	5.50	110	r90	1.50	30	r154	1.00	20	r218	1.50	30
r27	5.50	110	r91	1.50	30	r155	1.00	20	r219	1.50	30
r28	5.00	100	r92	1.50	30	r156	1.00	20	r220	1.50	30
r29	5.00	100	r93	1.50	30	r157	1.00	20	r221	1.50	30
r30	5.00	100	r94	1.50	30	r158	1.00	20	r222	1.50	30
r31	4.50	90	r95	1.50	30	r159	1.00	20	r223	1.50	30
r32	4.50	90	r96	1.50	30	r160	1.00	20	r224	1.50	30
r33	4.50	90	r97	1.50	30	r161	1.00	20	r225	2.00	40
r34	4.00	80	r98	1.50	30	r162	1.00	20	r226	2.00	40
r35	4.00	80	r99	1.50	30	r163	1.00	20	r227	2.00	40
r36	4.00	80	r100	1.50	30	r164	1.00	20	r228	2.00	40
r37	4.00	80	r101	1.50	30	r165	1.00	20	r229	2.00	40
r38	3.75	75	r102	1.50	30	r166	1.00	20	r230	2.50	50
r39	3.75	75	r103	1.50	30	r167	1.00	20	r231	2.50	50
r40	3.50	70	r104	1.50	30	r168	1.00	20	r232	2.50	50
r41	3.50	70	r105	1.50	30	r169	1.00	20	r233	3.00	60
r42	3.50	70	r106	1.50	30	r170	1.00	20	r234	3.00	60
r43	3.50	70	r107	1.50	30	r171	1.00	20	r235	3.00	60
r44	3.25	65	r108	1.50	30	r172	1.00	20	r236	3.50	70
r45	3.25	65	r109	1.50	30	r173	1.00	20	r237	3.50	70
r46	3.00	60	r110	1.25	25	r174	1.00	20	r238	4.00	80
r47	3.00	60	r111	1.25	25	r175	1.00	20	r239	4.00	80
r48	3.00	60	r112	1.25	25	r176	1.00	20	r240	4.50	90
r49	3.00	60	r113	1.25	25	r177	1.00	20	r241	5.00	100
r50	3.00	60	r114	1.25	25	r178	1.00	20	r242	5.00	100
r51	3.00	60	r115	1.25	25	r179	1.00	20	r243	5.50	110
r52	2.75	55	r116	1.25	25	r180	1.00	20	r244	6.00	120
r53	2.75	55	r117	1.25	25	r181	1.00	20	r245	6.50	130
r54	2.75	55	r118	1.25	25	r182	1.00	20	r246	7.00	140
r55	2.75	55	r119	1.25	25	r183	1.00	20	r247	7.50	150
r56	2.50	50	r120	1.25	25	r184	1.00	20	r248	8.00	160
r57	2.50	50	r121	1.25	25	r185	1.00	20	r249	8.50	170
r58	2.50	50	r122	1.25	25	r186	1.00	20	r250	9.00	180
r59	2.50	50	r123	1.25	25	r187	1.00	20	r251	9.50	190
r60	2.50	50	r124	1.25	25	r188	1.00	20	r252	10.50	210
r61	2.50	50	r125	1.25	25	r189	1.00	20	r253	11.50	230
r62	2.25	45	r126	1.00	20	r190	1.00	20	r254	12.50	250
r63	2.25	45	r127	1.00	20	r191	1.00	20	r255	25.00	500

5. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format: 8 bits × 1 RGB (3 dots)

Input width: 12 bits x double edge (1-pixel data)

(1) R/L = H (Right shift)

Output	S ₁	S ₂	S ₃	S ₄	...	S ₄₇₉	S ₄₈₀
Data	D _{00P} to D _{03P} , D _{00N} to D _{03N}	D _{10P} to D _{13P} , D _{10N} to D _{13N}	D _{20P} to D _{23P} , D _{20N} to D _{23N}	D _{00P} to D _{03P} , D _{00N} to D _{03N}	...	D _{10P} to D _{13P} , D _{10N} to D _{13N}	D _{20P} to D _{23P} , D _{20N} to D _{23N}

(2) R/L = L (Left shift)

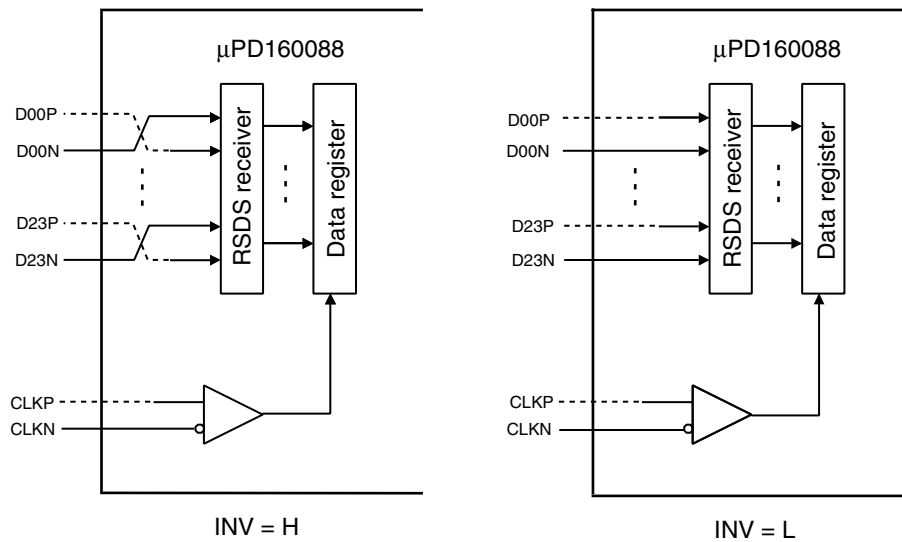
Output	S ₁	S ₂	S ₃	S ₄	...	S ₄₇₉	S ₄₈₀
Data	D _{00P} to D _{03P} , D _{00N} to D _{03N}	D _{10P} to D _{13P} , D _{10N} to D _{13N}	D _{20P} to D _{23P} , D _{20N} to D _{23N}	D _{00P} to D _{03P} , D _{00N} to D _{03N}	...	D _{10P} to D _{13P} , D _{10N} to D _{13N}	D _{20P} to D _{23P} , D _{20N} to D _{23N}

POL	S _{2n-1} ^{Note}	S _{2n} ^{Note}
H	V ₀ -V ₈	V ₉ -V ₁₇
L	V ₉ -V ₁₇	V ₀ -V ₈

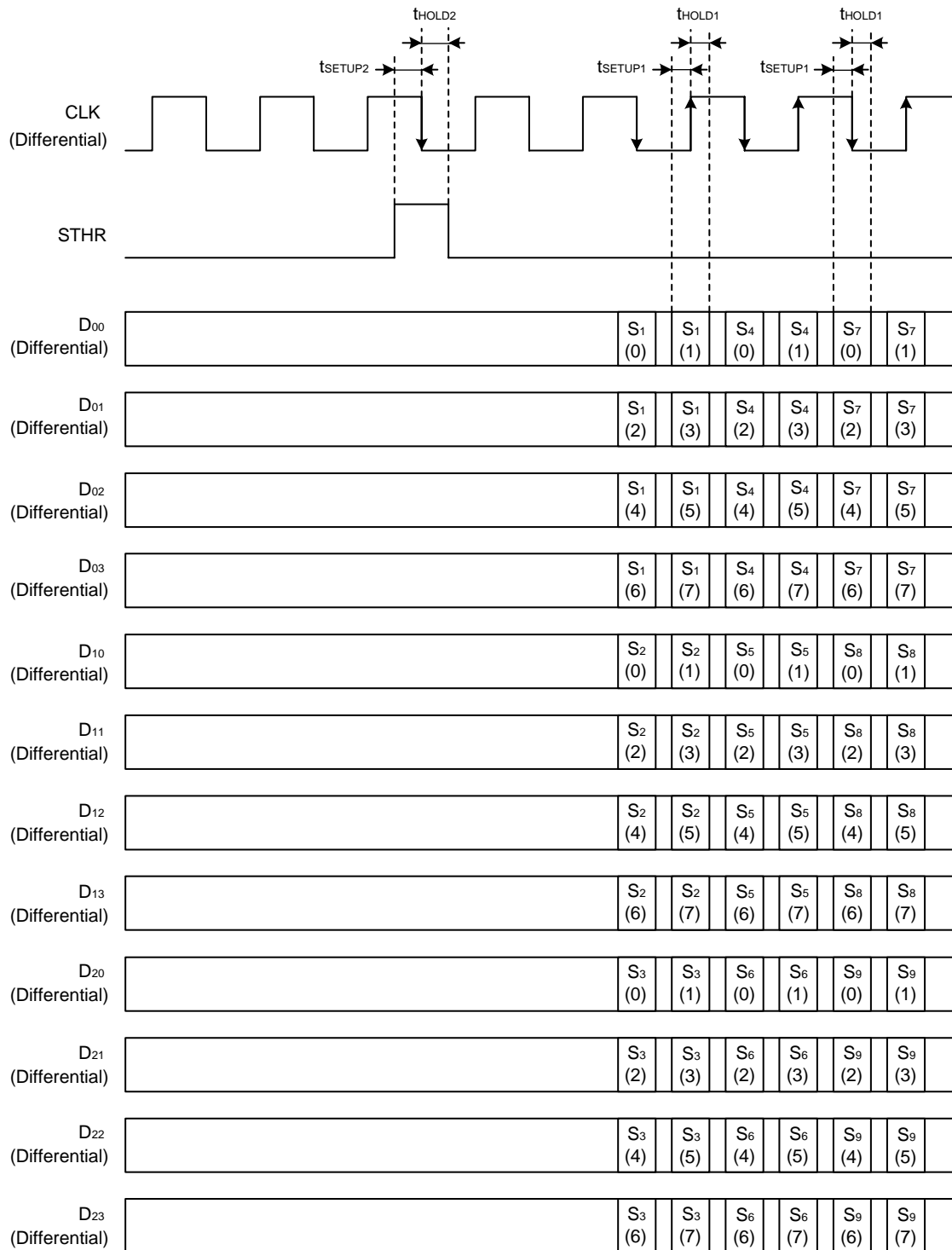
Note S_{2n-1} (Odd output), S_{2n} (Even output)

6. DATA INVERSION (INV)

INV controls the internal data inversion. When INV = H, the internal data is inverted and CLK is not inverted (See the figure as below). Using the INV pin, the RSDS data bus interface can be changed.



7. TIMING CHART AND RELATIONSHIP BETWEEN 8-BIT DATA AND DATA BUS LINE



Remark S_{n(0)}: LSB, S_{n(7)}: MSB

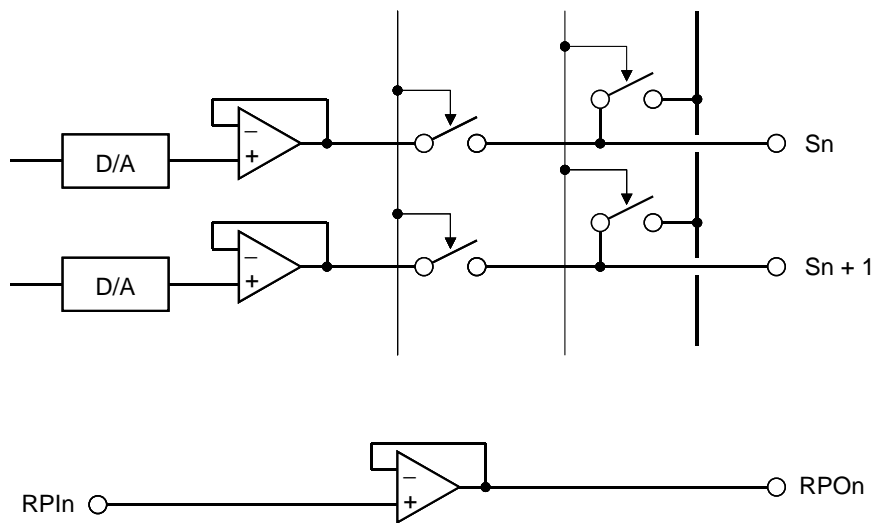
8. OUTPUT AMPLIFIER

This driver IC has two additional amplifiers called "Repair AMP" in both side of the IC for driving the repaired line. And these amplifiers have more driving ability than normal amplifier for S₁ to S₄₈₀. So it is recommended to evaluate its characteristic before the production if using.

<Feature of Repair AMP>

- (1) The pull-up and pull-down resistor is not prepared in input pin for the characteristic.
- (2) The driving ability is higher than the normal amplifier.
- (3) "Hi-Z" and "Output Reset" function doesn't work.

<Block Diagram>



9. RELATIONSHIP BETWEEN MODE, STB, POL AND OUTPUT WAVEFORM

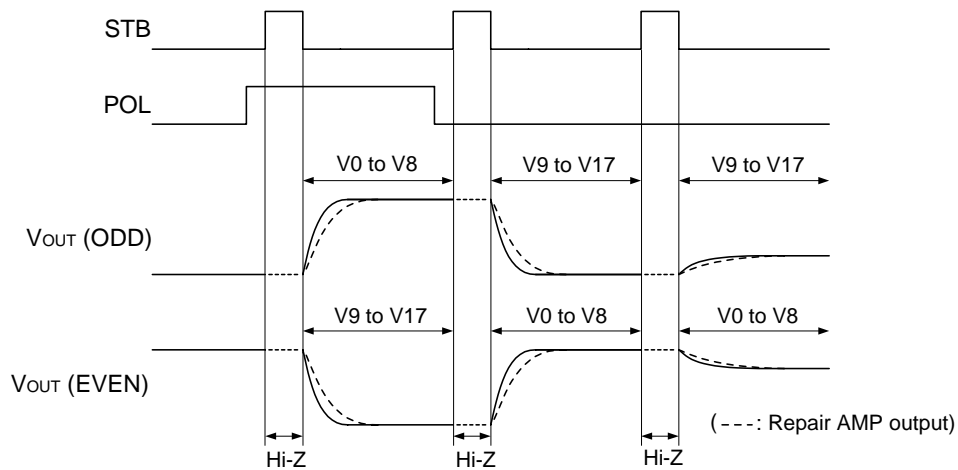
This driver IC has a "Charge Sharing" function that can be controlled by MODE pin. Refer to the following description of the detail function and decide to use this function after considering the suitable driving method.

MODE	Charge Sharing	Description of Charge Sharing
H or Open	Disable	"Charge Sharing" doesn't work.
L	Enable	"Charge Sharing" works during STB = H period only when the polarity is changed by switching POL signal. When POL signal is not switching, this function doesn't work.

< MODE = H or Open >

All outputs always become Hi-Z condition during STB = H in this mode. And "Charge Sharing" function doesn't work and all output always start at the falling edge of STB (Refer to **Figure 9-1.**).

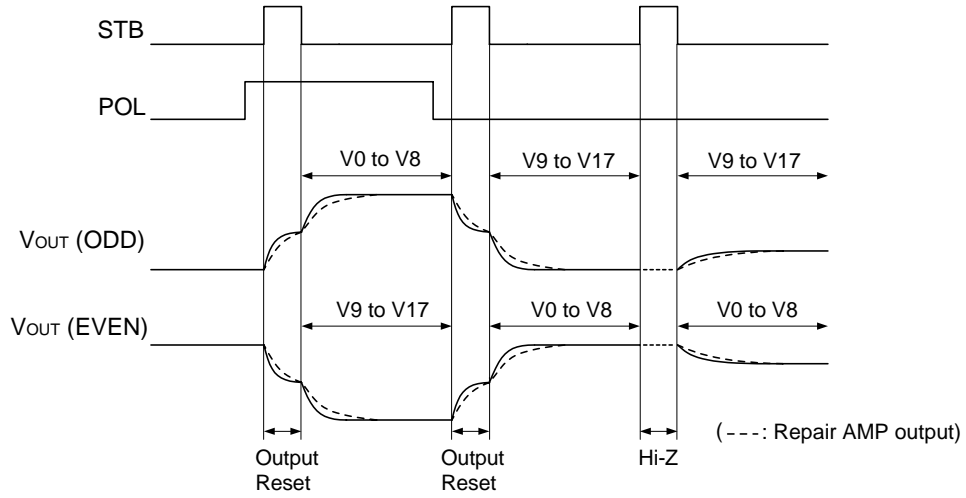
Figure 9-1. MODE = H or Open



<MODE = L>

"Charge Sharing" function works during STB = H in this mode. So all outputs are started at the falling edge of STB. But "Charge Sharing" function works only when POL signal is changed. So All output become Hi-Z condition during STB = H without any change of POL signal (Refer to **Figure 9-2**).

Figure 9-2. MODE = L



10. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings (T_A = +25°C, V_{SS1/D/A} = V_{SS2} = 0 V)

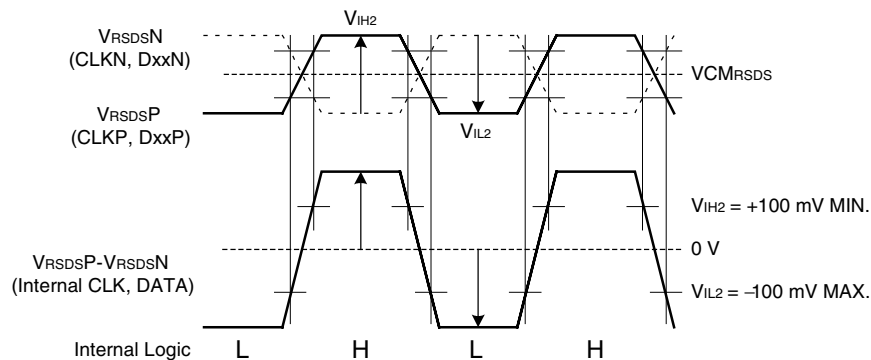
Parameter	Symbol	Ratings	Unit
Logic Part Supply Voltage	V _{DD1/D/A}	-0.5 to +4.0	V
Driver Part Supply Voltage	V _{DD2}	-0.3 to +14.0	V
Logic Part Input Voltage	V _{I1}	-0.5 to V _{DD1} + 0.5	V
Driver Part Input Voltage	V _{I2}	-0.3 to V _{DD2} + 0.3	V
Logic Part Output Voltage	V _{O1}	-0.5 to V _{DD1} + 0.5	V
Driver Part Output Voltage	V _{O2}	-0.5 to V _{DD2} + 0.5	V
Operating Ambient Temperature	T _A	-10 to +75	°C
Storage Temperature	T _{stg}	-55 to +125	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Recommended Operating Range (T_A = -10 to +75°C, V_{SS1/D/A} = V_{SS2} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Logic Part Supply Voltage	V _{DD1/D/A}		2.7	3.3	3.6	V	
Driver Part Supply Voltage	V _{DD2}		10.5	12.0	13.5	V	
High-Level Input Voltage1	V _{IH1}		0.7 V _{DD1}		V _{DD1}	V	
Low-Level Input Voltage1	V _{IL1}		0		0.3 V _{DD1}	V	
High-Level Input Voltage2 (Differential : V _{RSDS} P-V _{RSDS} N)	V _{IH2}	CLK, D _{xy} (x = 0 to 2) (y = 0 to 3)	V _{CM} = +1.2 V ^{Note}	+100	+200		mV
Low-Level Input Voltage2 (Differential : V _{RSDS} P-V _{RSDS} N)	V _{IL2}				-200	-100	
Common mode Input Voltage	V _{CM}	V _{DIFF} = 200 mV _{P-P} ^{Note}	0.5	1.2	1.4	V	
Driver Part Output Voltage	V _O	S1 to S480, RPO1, RPO2	0.1		V _{DD2} - 0.1	V	
γ- Corrected Voltage	V _n	V ₀ -V ₈	0.5 V _{DD2}		V _{DD2} - 0.1	V	
		V ₉ -V ₁₇	0.1		0.5 V _{DD2}	V	
Clock Frequency	f _{CLK}	V _{CM} = 1.2 V, V _{DIFF} = 200 mV _{P-P}			85	MHz	

Note



Remark V_{CM} = (V_{CLKP} + V_{CLKN}) / 2 or = (V_{DxxP} + V_{DxxN}) / 2 (x = 0, 1, 2)
V_{DIFF} = (V_{CLKP} - V_{CLKN}) or = (V_{DxxP} - V_{DxxN}) (x = 0, 1, 2)

Electrical Characteristics (T_A = -10 to +75°C, V_{DD1} = 2.7 to 3.6 V, V_{DD2} = 10.5 to 13.5 V, V_{SS1} = V_{SS2} = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input Leak Current	I _{IL}				±1.0	μA
High-Level Output Voltage	V _{OH}	STHR (STHL), I _{OH} = 0 mA	V _{DD1} - 0.4		V _{DD1}	V
Low-Level Output Voltage	V _{OL}	STHR (STHL), I _{OL} = 0 mA	V _{SS1}		V _{SS1} + 0.4	V
γ- Corrected Resistance	R _γ	V _{DD2} = 12.0 V, T _A = 25°C, V ₀ -V ₈ = V ₉ -V ₁₇ = 5.0 V	11.91	17.02	22.13	kΩ
Pull-up/Pull-down Resistance	R _{PU}	V _{DD1} = 3.3 V MODE, LPC, TEST	80	200	500	kΩ
Driver Output Current	I _{VOH}	S ₁ to S ₄₈₀ , V _X = 11 V, V _{OUT} = 10.5 V ^{Note1}			-70	μA
	I _{VOL}	RPO1, RPO2 V _X = 1.0 V, V _{OUT} = 1.5 V ^{Note1} V _{DD2} = 12.0 V	70			μA
Output Voltage Deviation (DV _O)	ΔV _O	V _O = 1.5 V to V _{DD2} - 1.5 V		±12	±20	mV
		V _O = 0.1 to 1.5 V		±40	±50	mV
		V _O = V _{DD2} - 1.5 V to V _{DD2} - 0.1 V				
Output Swing Voltage Difference Deviation (DV _{RMS})	ΔV _{p-p1}	V _O = 1.5 V to V _{DD2} - 1.5 V		±6	±10	mV
	ΔV _{p-p2}	V _O = 0.1 to 1.5 V V _O = V _{DD2} - 1.5 V to V _{DD2} - 0.1 V		±30	±50	mV
Output Swing Voltage Average Deviation	AV _O	Input data: 80H		±1	± 7.5	mV
Logic Part Dynamic Current Consumption1	I _{DD11}	V _{DD1} ^{Note2, 3, 4}		3.0 ^{Note2}	6.0 ^{Note3}	mA
Logic Part Dynamic Current Consumption2	I _{DD12}	V _{DD1} ^{Note2, 3, 4}		3.0 ^{Note4}	6.0 ^{Note5}	mA
Driver Part Dynamic Current Consumption	I _{DD2}	V _{DD2} , with no load, RPI1 and RPI2 (IN) are not floating		13 ^{Note6}	25 ^{Note7}	mA

Notes 1. V_X refers to the voltage applied to analog output pins S₁ to S₄₈₀.

V_{OUT} refers to the output voltage of analog output pins S₁ to S₄₈₀.

2. f_{CLKP}, f_{CLKN} = 67.5 MHz, f_{STB} = 80.0 kHz, test pattern = 55H or AAH, T_A = 25°C, V_{DD1} = 3.0 V
3. f_{CLKP}, f_{CLKN} = 67.5 MHz, f_{STB} = 80.0 kHz, test pattern = 55H or AAH, V_{DD1} = 3.6 V
4. f_{CLKP}, f_{CLKN} = 54.0 MHz, f_{STB} = 64.9 kHz, test pattern = 55H or AAH, T_A = 25°C, V_{DD1} = 3.0 V
5. f_{CLKP}, f_{CLKN} = 54.0 MHz, f_{STB} = 64.9 kHz, test pattern = 55H or AAH, V_{DD1} = 3.6 V
6. f_{CLKP}, f_{CLKN} = 67.5 MHz, f_{STB} = 80.0 kHz, test pattern = 00H, T_A = 25°C, V_{DD2} = 12.0 V
7. f_{CLKP}, f_{CLKN} = 67.5 MHz, f_{STB} = 80.0 kHz, test pattern = 00H, V_{DD2} = 13.5 V

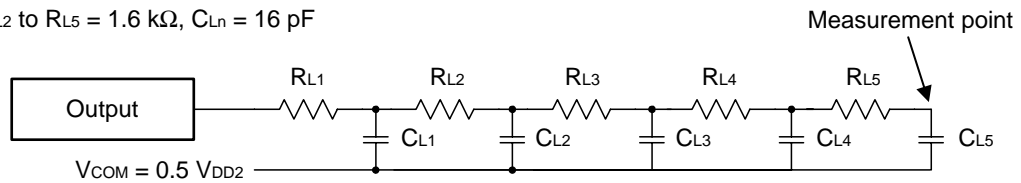
Switching Characteristics ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.7$ to 3.6 V, $V_{DD2} = 10.5$ to 13.5 V, $V_{SS1} = V_{SS2} = 0$ V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t_{PLH1}	$C_L = 15$ pF		6	10	ns
Driver Output Delay Time 1	t_{PLH2} ^{Note1}	$V_{DD2} = 12.0$ V S_1 to S_{480} $R_L = 9$ kΩ, $C_L = 80$ pF		2.5	5.0	μs
	t_{PLH3} ^{Note2}			4.0	8.0	μs
	t_{PHL2} ^{Note1}			2.5	5.0	μs
	t_{PHL3} ^{Note2}			4.0	8.0	μs
Driver Output Delay Time 2	t_{PLH4} ^{Note1}	$V_{DD2} = 12.0$ V RPO1, RPO2 $R_L = 9$ kΩ, $C_L = 80$ pF + 150 pF		2.0	5.0	μs
	t_{PLH5} ^{Note2}			4.0	8.0	μs
	t_{PHL4} ^{Note1}			2.0	5.0	μs
	t_{PHL5} ^{Note2}			4.0	8.0	μs
Input Capacitance	C_{i1}	Logic input besides STHR (STHL), $T_A = 25^\circ\text{C}$		4	10	pF
	C_{i2}	STHR (STHL), $T_A = 25^\circ\text{C}$		4	15	pF

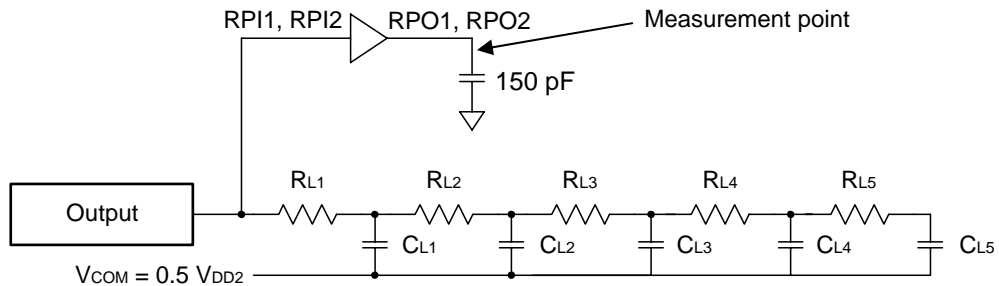
- Notes 1.** The value is specified when the drive voltage value reaches the target output voltage level of 10 or 90%.
2. The value is specified when the drive voltage value reaches the target output voltage level of 8-bit accuracy.

<Test condition>

$R_{L1} = 2.6$ kΩ, R_{L2} to $R_{L5} = 1.6$ kΩ, $C_{Ln} = 16$ pF



$R_{L1} = 2.6$ kΩ, R_{L2} to $R_{L5} = 1.6$ kΩ, $C_{Ln} = 16$ pF



Timing Requirement ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.7$ to 3.6 V, $V_{SS1} = 0$ V, $t_r = t_f = 3.0$ ns (CMOS), $t_r = t_f = 1.0$ ns (RSDS))

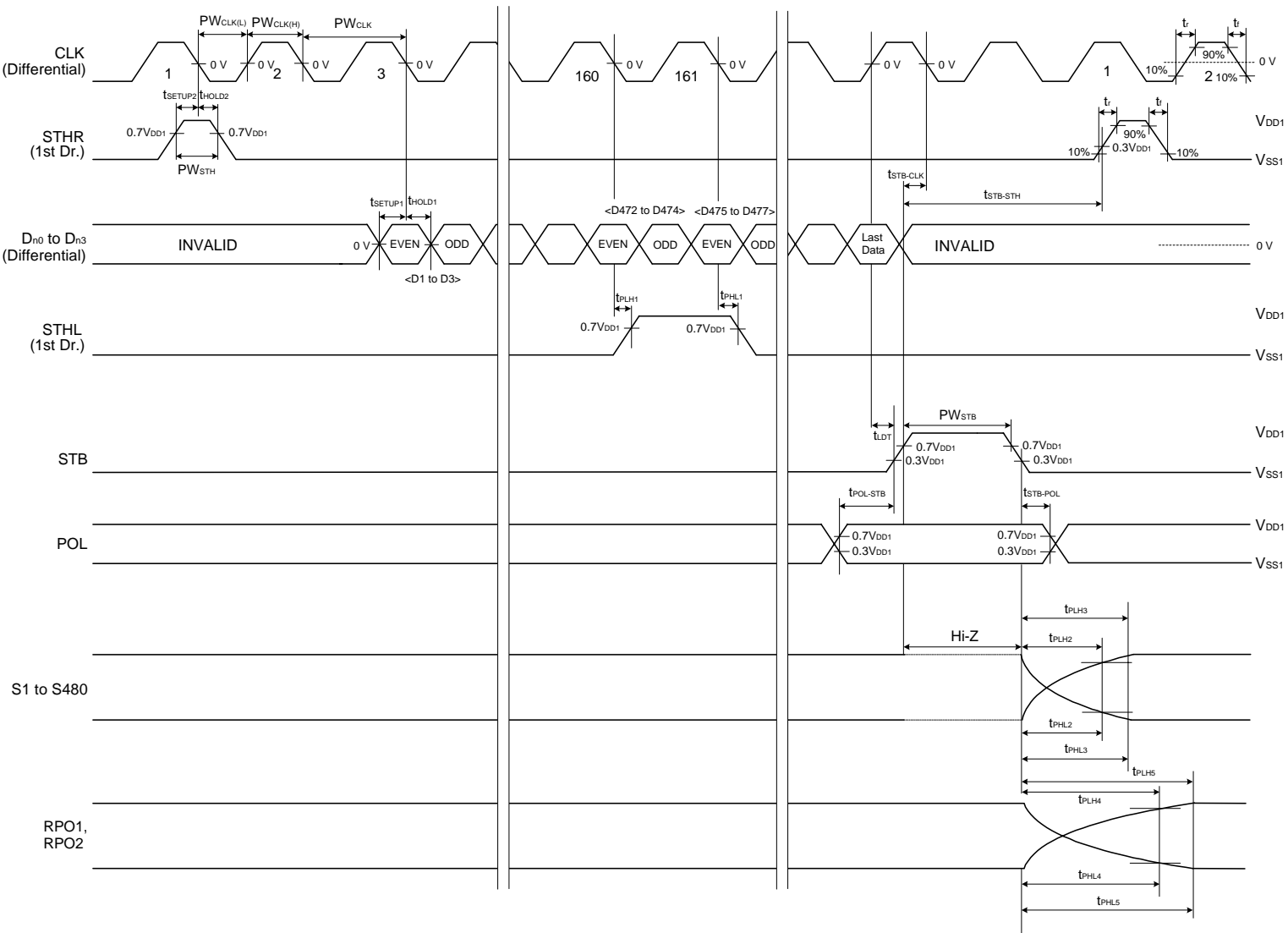
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Period	PW _{CLK}		11.8			ns
Clock Pulse High Period	PW _{CLK(H)}		4			ns
Clock Pulse Low Period	PW _{CLK(L)}		4			ns
Data Setup Time	t _{SETUP1}		2			ns
Data Hold Time	t _{HOLD1}		0			ns
Start Pulse Setup Time	t _{SETUP2}		1			ns
Start Pulse Hold Time	t _{HOLD2}		2			ns
Start Pulse High Level Width	PW _{STH}		1		2	CLKP
STB Pulse High Level Width	PW _{STB}		1			μs
Last Data Timing	t _{LDT}		1			CLKP
STB-CLK Time	t _{STB-CLK}	STB ↑ → CLKP-N↓	3			ns
Time Between STB and Start Pulse	t _{STB-STH}	STB ↓ → STHR(STHL) ↑	5			CLKP
POL-STB Time	t _{POL-STB}	POL ↑ or ↓ → STB ↑	14			ns
STB-POL Time	t _{STB-POL}	STB ↓ → POL ↓ or ↑	10			ns

Remark t_r and t_f are defined 10 to 90% of each signal amplitude.

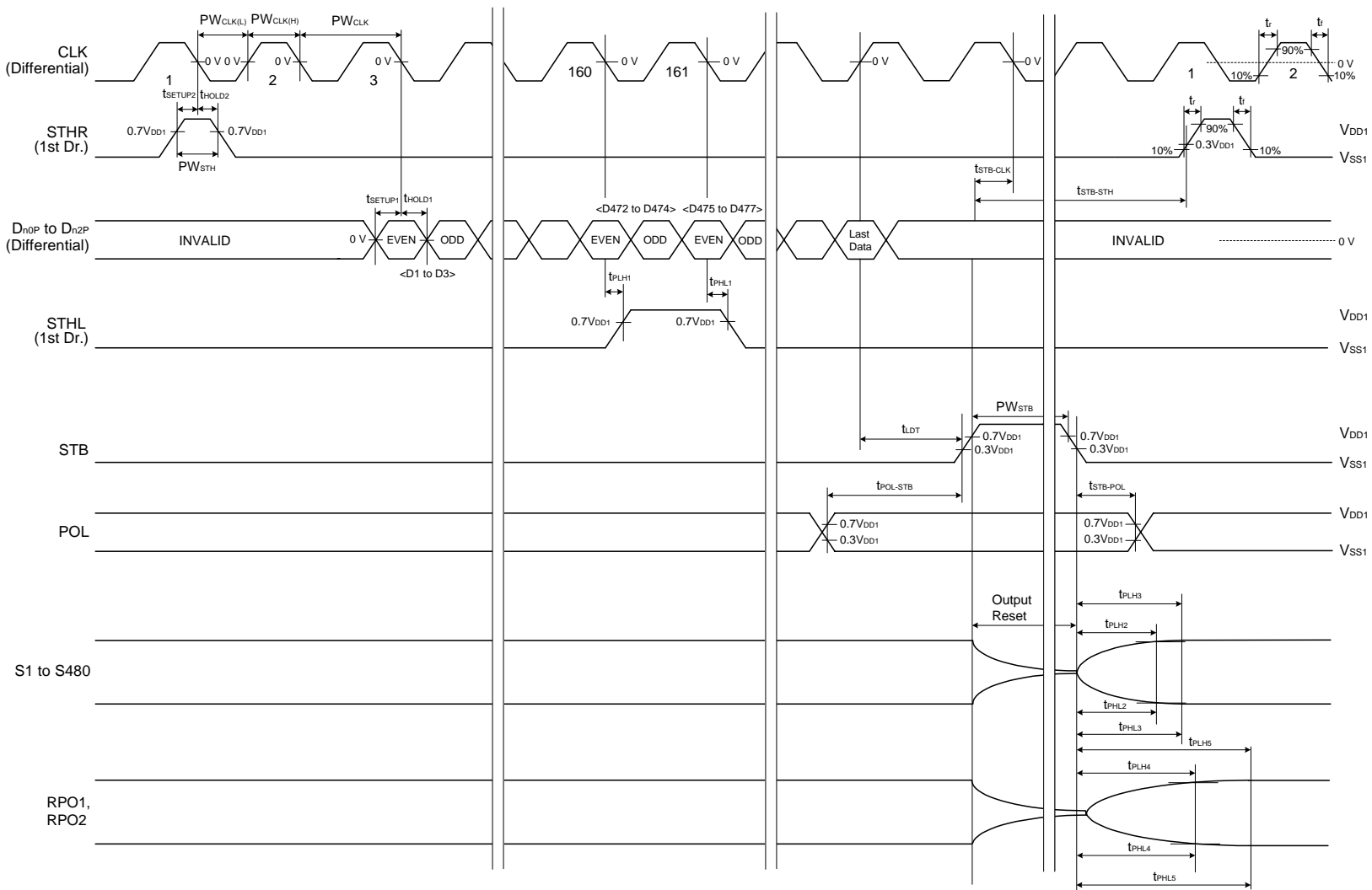
Switching Characteristics Waveform (R_I/L = H)

Unless otherwise specified, the input level is defined to be V_{IH} = 0.7 V_{DD1}, V_{IL} = 0.3 V_{DD1} at CMOS signal and 0 V at differential signal (RSDS).

<MODE = H or Opens>



<MODE = L>



11. RECOMMENDED MOUNTING CONDITIONS

The following conditions must be met for mounting conditions of the μPD160088.

For more details, refer to the

[Semiconductor Device Mounting Manual] (<http://www.necel.com/pkg/en/mount/index.html>)

Please consult with our sales offices in case other mounting process is used, or in case the mounting is done under different conditions.

μPD160088N-xxx: TCP (TAB Package)

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C, heating for 2 to 3 seconds : pressure 100g (per solder)
	ACF (Adhesive Conductive Film)	Temporary bonding 70 to 100°C: pressure 3 to 8 kg/cm ² : time 3 to 5 sec. Real bonding 165 to 180°C: pressure 25 to 45 kg/cm ² : time 30 to 40 sec. (When using the anisotropy conductive film SUMIZAC1003 of Sumitomo Bakelite,Ltd).

Caution To find out the detailed conditions for mounting the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more mounting methods at a time.

NOTES FOR CMOS DEVICES**① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN**

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

Reference Documents**NEC Semiconductor Device Reliability/Quality Control System (C10983E)****Quality Grades On NEC Semiconductor Devices (C11531E)**

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